

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01	100.0	1.02
			<b>Subtotal</b>	<b>0.01</b>	<b>100</b>	<b>1.02</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.46
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	4.86
	Copper alloy	Copper (Cu)	7440-50-8	66.23	99.87	4849.69
			<b>Subtotal</b>	<b>66.32</b>	<b>100</b>	<b>4856.01</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.33	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.98	15.0	364.5
	Filler	Silica fused	60676-86-0	24.56	74.0	1798.2
	Flame retardant	Metal hydroxide		2.32	7.0	170.1
			<b>Subtotal</b>	<b>33.19</b>	<b>100</b>	<b>2430</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.41	100.0	30
			<b>Subtotal</b>	<b>0.41</b>	<b>100</b>	<b>30</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05	100.0	3.4
			<b>Subtotal</b>	<b>0.05</b>	<b>100</b>	<b>3.4</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	65.0	1.5
	Lead alloy	Silver (Ag)	7440-22-4	0.01	25.0	0.57
	Lead alloy	Antimony (Sb)	7440-36-0	0	10.0	0.23
			<b>Subtotal</b>	<b>0.03</b>	<b>100</b>	<b>2.3</b>
			<b>Total</b>	<b>100.01</b>	<b>100</b>	<b>7322.73</b>

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